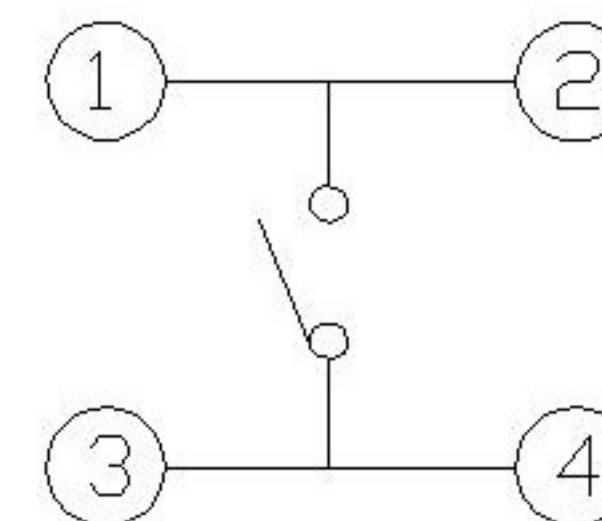
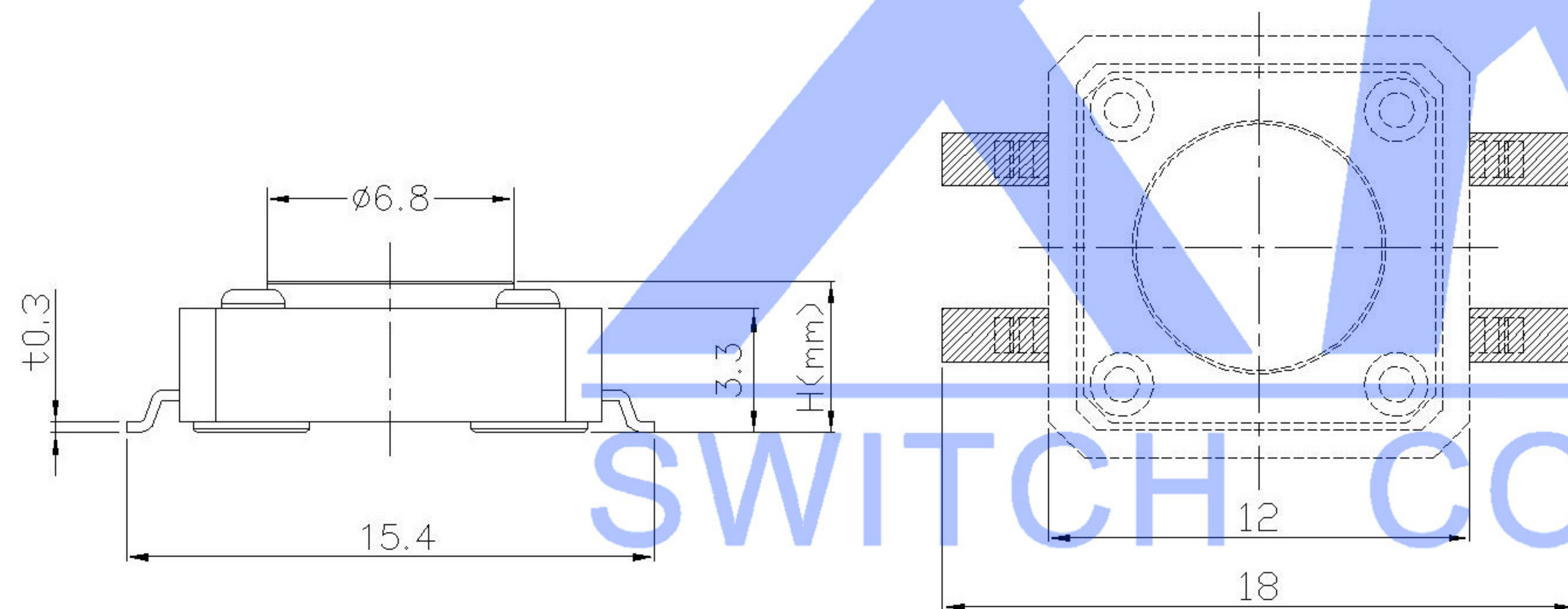


CIRCUIT DIAGRAM



Code-X	H	Code-X	H
A	4.3	O	11.0
B	4.5	P	11.5
C	5.0	Q	12
D	5.5	R	12.5
E	6.0	S	13.0
F	6.5	T	13.5
G	7.0	U	14.0
H	7.5	V	15.0
I	8.0	W	15.5
J	8.5	X	16
K	9.0	Y	17
L	9.5	Z	18
M	10.0	19	19
N	10.5		

P.C.B MOUNTING PATTERN DIMENSION
The following soldering patterns are recommended for reflow soldering



SPECIFICATION

Contact Rating: 50mA,12V DC
 Contact Resistance: 100mΩ max
 Insulation Resistance: 100mΩ min.500V DC
 Dielectric Strength: 250V AC/1minute
 Travel: 0.25mm
 Operating Temp: -30°C~+85°C
 Storage Temp: -30°C~+80°C

PAPT NO	TS-1103S-X-X
Operating Force	B: 160gf C: 260gf
Height	Code-X

ITEM	PAPT NAMF	TER.NO	QTY	MATERIAL	FINISHING	REMARK
⑤	Terminal	—	4	Brass (0.30t)	Plating silvering	—
④	Contact	—	1	F.ag/Sus	Natural	—
③	Base	—	1	Pa46	—	—
②	Cover	—	1	Spcc	Plating Nickel	—
①	Keystake	—	1	Pa46	—	—

MARK	DESCRIPTION	DATE	REVISED	APPROVED	units: mm	DSND	DATE	SCALE: N/A	MODEL TYPE: TACT SWITCH
ΔX					tolerance:	DWN	DATE	VIEW:	PART NO.:
					X.X ±0.2mm	CHKD	DATE	UNIT: mm	DWG NO.:
					X.XX ±0.1mm	APPD	DATE	SIZE: A4	TS-1103S-X-X
					X.XXX ±0.05mm	XKB INDUSTRIAL PRECISION CO.,LIMITED			WEIGHT 1.0g
REVISIONS					UNSPECIFIED TOLERANCES				SHEET 1/1
www.xk-dg.cn www.helloxkb.com www.helloxkb.cn									REVISION A0